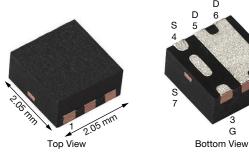


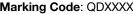
www.vishay.com

Vishay Siliconix

# Automotive N-Channel 60 V (D-S) 175 °C MOSFET

### PowerPAK® SC-70-6L Single





Package

Marking Code: QDXXXX										
PRODUCT SUMMARY										
V <sub>DS</sub> (V)	60									
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.032									
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.048									
I <sub>D</sub> (A)	9									
Configuration	Single									

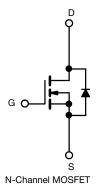
#### **FEATURES**

- TrenchFET® power MOSFET
- AEC-Q101 qualified <sup>d</sup>
- 100 % Rq and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





HALOGEN FREE



PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-source voltage		V <sub>DS</sub>	60	V		
Gate-source voltage		V <sub>GS</sub>	± 20			
0	T <sub>C</sub> = 25 °C		9			
Continuous drain current a	T <sub>C</sub> = 125 °C	I <sub>D</sub>	8.3			
Continuous source current (diode conduct	ion) <sup>a</sup>	I <sub>S</sub>	9	Α		
Pulsed drain current <sup>a</sup>		I <sub>DM</sub>	24.5			
Single pulse avalanche current	. 0.4	I <sub>AS</sub>	13			
Single pulse avalanche energy	L = 0.1 mH	E <sub>AS</sub>	8.4	mJ		
Maximum navvar dissination b	T <sub>C</sub> = 25 °C		13.6	W		
Maximum power dissipation <sup>b</sup>	T <sub>C</sub> = 125 °C	$P_{D}$	4.5			
Operating junction and storage temperatur	e range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	00		
Soldering recommendations (peak temperature)	ature) <sup>e, f</sup>	Ü	260	°C		

THERMAL RESISTANCE RATINGS									
PARAMETER		SYMBOL	LIMIT	UNIT					
Junction-to-ambient	PCB mount c		90	°C/W					
Junction-to-case (drain)		$R_{thJC}$	11	C/VV					

#### Notes

- a. Package limited
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %
- c. When mounted on 1" square PCB (FR4 material)
- d. Parametric verification ongoing

S18-0149-Rev. A, 05-Feb-18

- e. See solder profile (www.vishay.com/doc?73257). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- f. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

PowerPAK SC-70



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PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT		
Static	-				I.	I.	ı	
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60	-	-	V	
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	· V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.5	2	2.5	V	
Gate-source leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	= 0 V, V <sub>GS</sub> = ± 8 V	-	-	± 100	nA	
		$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V	-	-	1		
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ	
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C	-	-	250		
On-state drain current a	I <sub>D(on)</sub>	V <sub>GS</sub> = 4.5 V	$V_{DS} \ge 5 V$	10	-	-	Α	
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 3 A	- 0.026 0		0.032		
Drain-source on-state resistance <sup>a</sup>		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 3 A, T <sub>J</sub> = 125 °C	-	-	0.058	Ω	
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 3 A, T <sub>J</sub> = 175 °C	-	-	0.065		
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 3 A	-	0.045	0.048		
Forward transconductance b	9fs	V <sub>DS</sub>	-	21	-	S		
Dynamic <sup>b</sup>								
Input capacitance	C <sub>iss</sub>				509	636		
Output capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	-	242	302	pF	
Reverse transfer capacitance	C <sub>rss</sub>			-	14.6	18.3		
Total gate charge <sup>c</sup>	Qg			-	7.75	9.7		
Gate-source charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 30 \text{ V}, I_{D} = 5 \text{ A}$	-	1.53		nC	
Gate-drain charge <sup>c</sup>	$Q_{gd}$			-	1.2	-		
Gate resistance	R <sub>g</sub>	f = 1 MHz		0.24	0.41	0.65	Ω	
Turn-on delay time <sup>c</sup>	t <sub>d(on)</sub>			-	7.3	9.1		
Rise time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, R_L = 6 \Omega$		-	2	2.5	ns	
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>	I <sub>D</sub> ≅ 5 A, V	-	12	15.5			
Fall time <sup>c</sup>	t <sub>f</sub>	1	-	1.4	1.8			
Source-Drain Diode Ratings and Char	acteristics <sup>b</sup>							
Pulsed current <sup>a</sup>	I <sub>SM</sub>			-	-	24	Α	
Forward voltage	$V_{SD}$	I <sub>F</sub> =	-	0.75	1.2	V		

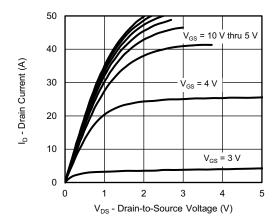
### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

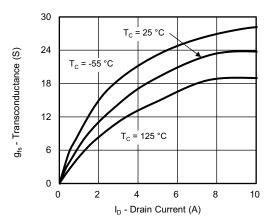
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



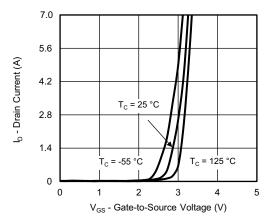
### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



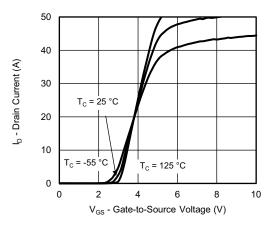
#### **Output Characteristics**



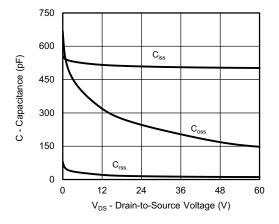
Transconductance



**Transfer Characteristics** 



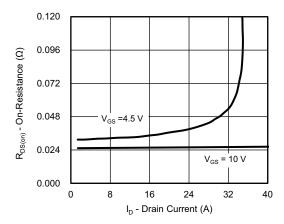
Transfer Characteristics



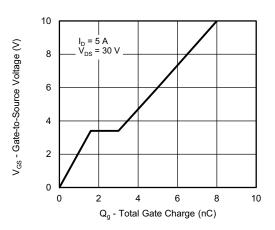
Capacitance



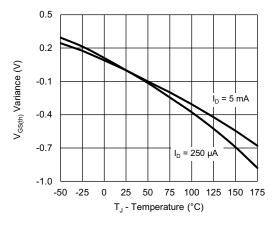
### TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



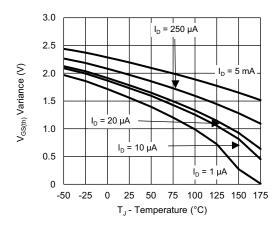
#### On-Resistance vs. Drain Current



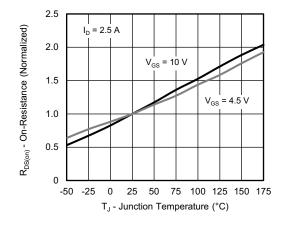
**Gate Charge** 



**Threshold Voltage** 



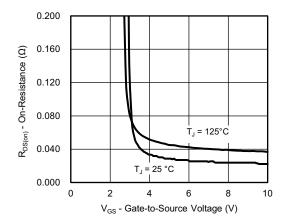
**Threshold Voltage** 



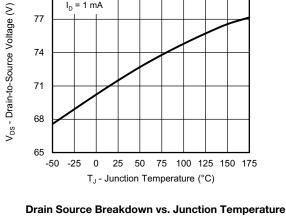
On-Resistance vs. Junction Temperature



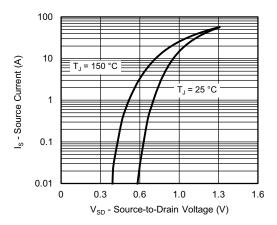
### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



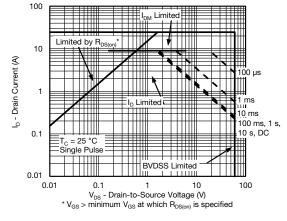
On-Resistance vs. Gate-to-Source Voltage



80



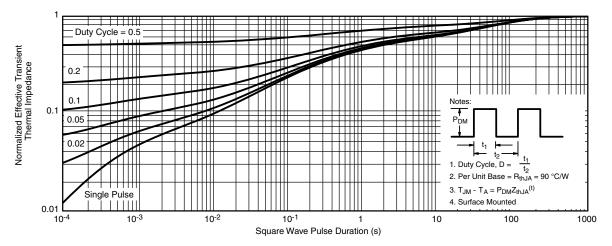
**Source Drain Diode Forward Voltage** 



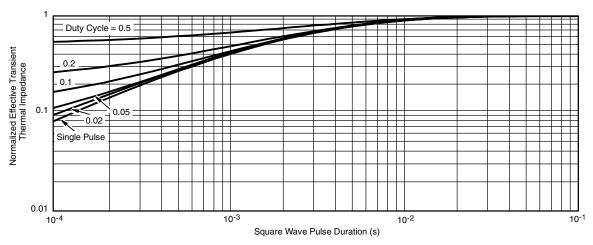
Safe Operating Area



### THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?75579">www.vishay.com/ppg?75579</a>.





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## PowerPAK® SC70-6L





BACKSIDE VIEW OF SINGLE

BACKSIDE VIEW OF DUAL



- All dimensions are in millimeters
  Package outline exclusive of mold flash and metal burr
  Package outline inclusive of plating

	SINGLE PAD						DUAL PAD						
DIM	MILLIMETERS			INCHES			MILLIMETERS			INCHES			
	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	
Α	0.675	0.75	0.80	0.027	0.030	0.032	0.675	0.75	0.80	0.027	0.030	0.032	
A1	0	-	0.05	0	-	0.002	0	-	0.05	0	-	0.002	
b	0.23	0.30	0.38	0.009	0.012	0.015	0.23	0.30	0.38	0.009	0.012	0.015	
С	0.15	0.20	0.25	0.006	0.008	0.010	0.15	0.20	0.25	0.006	0.008	0.010	
D	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085	
D1	0.85	0.95	1.05	0.033	0.037	0.041	0.513	0.613	0.713	0.020	0.024	0.028	
D2	0.135	0.235	0.335	0.005	0.009	0.013							
E	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085	
E1	1.40	1.50	1.60	0.055	0.059	0.063	0.85	0.95	1.05	0.033	0.037	0.041	
E2	0.345	0.395	0.445	0.014	0.016	0.018							
E3	0.425	0.475	0.525	0.017	0.019	0.021							
е		0.65 BSC			0.026 BSC	;	0.65 BSC			0.026 BSC			
K		0.275 TYP			0.011 TYP			0.275 TYP			0.011 TYP		
K1		0.400 TYP		0.016 TYP			0.320 TYP			0.013 TYP			
K2		0.240 TYP		0.009 TYP			0.252 TYP			0.010 TYP			
К3		0.225 TYP		0.009 TYP									
K4		0.355 TYP		0.014 TYP									
L	0.175	0.275	0.375	0.007	0.011	0.015	0.175	0.275	0.375	0.007	0.011	0.015	
T							0.05	0.10	0.15	0.002	0.004	0.006	

ECN: C-07431 - Rev. C, 06-Aug-07

DWG: 5934

06-Aug-07



### RECOMMENDED PAD LAYOUT FOR PowerPAK® SC70-6L Single



Dimensions in mm/(Inches)

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ATTLICATION NOT



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